

**MEC8-DV SERIES**

**(0,80 mm) .0315"**

# VERTICAL MICRO EDGE CARD SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-DV](http://www.samtec.com?MEC8-DV)

**Insulator Material:**  
Black LCP

**Contact Material:**  
Phosphor Bronze

**Plating:**  
Au or Sn over

50µ" (1,27 µm) Ni

**Operating Temp Range:**  
-55°C to +125°C

**Insertion Depth:**  
(4,22 mm) .166" to

(5,66 mm) .223"

**Current Rating:**  
1.8 A per pin

(6 adjacent pins powered)

**Voltage Rating:**  
185 VAC

**RoHS Compliant:**  
Yes

**Processing:**

**Lead-Free Solderable:**  
Yes

**SMT Lead Coplanarity:**  
(0,10 mm) .004" max (10-50)

(0,15 mm) .006" max (60-70)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## ALSO AVAILABLE (MOQ Required)

- 1 mm mating card thickness option
- Locking clip (Manual placement required)

Contact Samtec.

## OTHER SOLUTIONS

- Right Angle
- Edge Mount

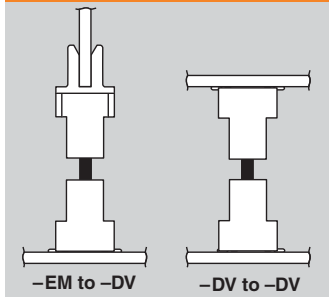
See [samtec.com?MEC8-RA](http://samtec.com?MEC8-RA) or [samtec.com?MEC8-EM](http://samtec.com?MEC8-EM)

**Note:** While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

**Note:** Some sizes, styles and options are non-standard, non-returnable.

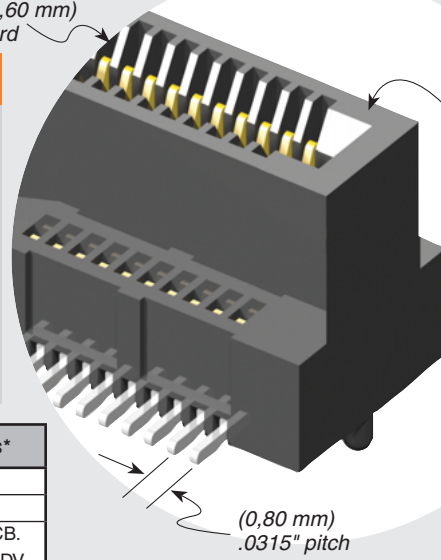
**Mates with:**  
(1,60 mm) .062" thick cards

## APPLICATIONS



Mates with (1,60 mm) .062" thick card

Variety of lead counts



MEC8-DV 8,65 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8.5 GHz / 17 Gbps
Differential Pair Signaling	8.0 GHz / 16 Gbps

\*Performance data includes effects of a non-optimized PCB.  
Complete test data available at [www.samtec.com?MEC8-DV](http://www.samtec.com?MEC8-DV) or contact [sig@samtec.com](mailto:sig@samtec.com)

**MEC8**

**1**

**POSITIONS PER ROW**

**02**

**PLATING OPTION**

**DV**

**OTHER OPTION**

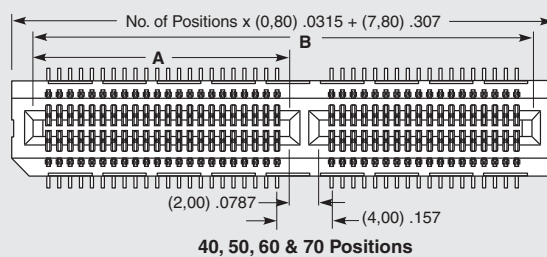
**10, 20, 30, 40, 50, 60, 70**

**-L**

= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

**-A**  
= Alignment Pin

**-K**  
= (5,50 mm) .217" DIA Polyimide Pick & Place Pad



POSITIONS PER ROW	A	B
40	(18,90) .744	(36,60) 1.441
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071
70	(30,90) 1.217	(60,60) 2.386

